

IMT65R083M1H-VB Datasheet

N-Channel 650V (D-S) SiC Power MOSFET

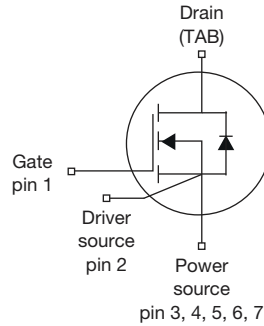
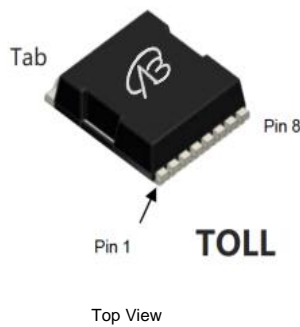
PRODUCT SUMMARY		
V_{DS} (V)	650	
$R_{DS(on)}$ at 25 °C (Ω)	$V_{GS} = 18$ V	0.055
Q_g (nC)	40	

FEATURES

- Low figure-of-merit (FOM) $R_{on} \times Q_g$
- Higher robustness and system reliability
- Kelvin source provides up to 4 times lower switching losses
- Ultra low gate charge (Q_g)
- Avalanche energy rated (UIS)

APPLICATIONS

- Server and telecom power supplies
- EV charging infrastructure
- Solar PV inverters
- DC/DC converter

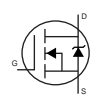


ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)				
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V_{DS}	650	V	
Gate-Source Voltage	V_{GS}	-10 / +22		
Continuous Drain Current ($T_J = 175$ °C)	V_{GS} at 18 V	$T_C = 25$ °C	35	A
		$T_C = 100$ °C	25	
Pulsed Drain Current ^a		I_{DM}	95	
Linear Derating Factor			2.1	W/°C
Single Pulse Avalanche Energy ^b		E_{AS}	160	mJ
Maximum Power Dissipation		P_D	192	W
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to +175	°C
Drain-Source Voltage Slope	$T_J = 125$ °C	dV/dt	150	V/ns
Reverse Diode dV/dt ^d			100	
Soldering Recommendations (Peak Temperature) ^c	for 10 s		260	°C

Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 50$ V, starting $T_J = 25$ °C, $L = 1$ mH, $R_g = 25$ Ω .
- 1.6 mm from case.
- $I_{SD} \leq I_D$, $dI/dt = 100$ A/ μ s, starting $T_J = 25$ °C.

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	62	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.78	

SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$		650	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$, $I_D = 1\text{ mA}$		-	0.70	-	V/°C
Gate-Source Threshold Voltage (N)	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 5\text{ mA}$		2	-	4.5	V
Gate-Source Leakage	I_{GSS}	$V_{GS} = +18\text{ V}$		-	-	100	nA
		$V_{GS} = -8\text{ V}$		-	-	100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 650\text{ V}, V_{GS} = 0\text{ V}$		-	10	-	μA
		$V_{DS} = 650\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$		-	-	100	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 18\text{ V}$	$I_D = 20\text{ A}$	-	0.055	-	Ω
Forward Transconductance	g_{fs}	$V_{DS} = 0\text{ V}, I_D = 20\text{ A}$		-	10	-	S
Dynamic							
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V},$ $V_{DS} = 600\text{ V},$ $f = 100\text{ KHz}$		-	1500	-	pF
Output Capacitance	C_{oss}			-	90	-	
Reverse Transfer Capacitance	C_{rss}			-	3	-	
Effective Output Capacitance, Energy Related ^a	$C_{o(er)}$	$V_{DS} = 0\text{ V to } 400\text{ V}, V_{GS} = 0\text{ V}$		-	120	-	
Effective Output Capacitance, Time Related ^b	$C_{o(tr)}$			-	160	-	
Total Gate Charge	Q_g	$V_{GS} = -5/18\text{ V}$	$I_D = 20\text{ A}, V_{DS} = 400\text{ V}$	-	40	-	nC
Gate-Source Charge	Q_{gs}			-	20	-	
Gate-Drain Charge	Q_{gd}			-	23	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 400\text{ V}, I_D = 20\text{ A}$ $V_{GS} = -5/15\text{ V}$		-	12	15	ns
Rise Time	t_r			-	10	13	
Turn-Off Delay Time	$t_{d(off)}$			-	20	-	
Fall Time	t_f			-	10	-	
Gate Input Resistance	R_g	$f = 1\text{ MHz}, \text{ open drain}$		-	8.2	-	Ω
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	30	A
Pulsed Diode Forward Current	I_{SM}			-	-	90	
Diode Forward Voltage	V_{SD}	$T_J = 25\text{ }^\circ\text{C}, I_S = 20\text{ A}, V_{GS} = 0$		-	-	4.1	V
Reverse Recovery Time	t_{rr}	$T_J = 25\text{ }^\circ\text{C}, I_F = I_S = 20\text{ A},$ $di/dt = 1000\text{ A}/\mu\text{s}, V_R = 400\text{ V}$		-	12	-	ns
Reverse Recovery Charge	Q_{rr}			-	0.06	-	μC
Reverse Recovery Current	I_{RRM}			-	10	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 60 % V_{DSS} .
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 60 % V_{DSS} .

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

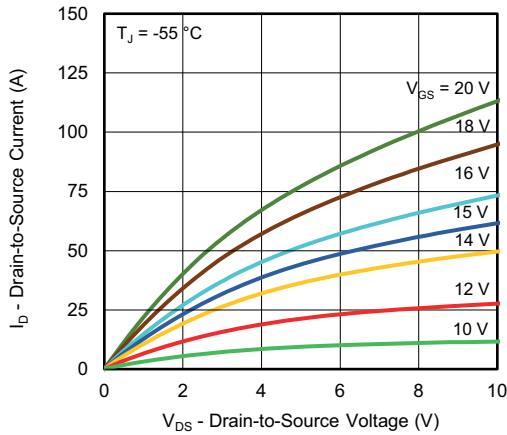


Fig. 1 - Typical Output Characteristics

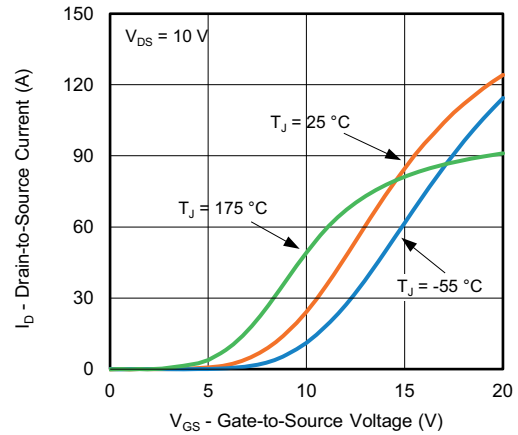


Fig. 4 - Typical Transfer Characteristics

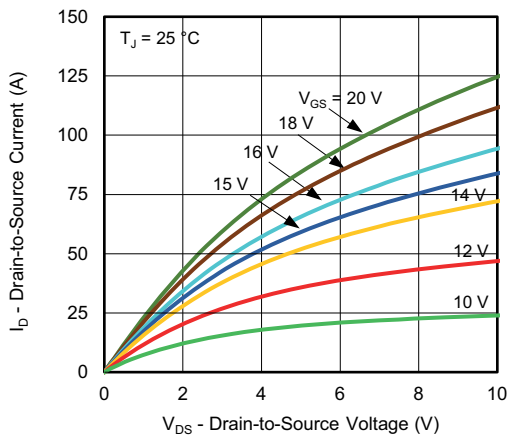


Fig. 2 - Typical Output Characteristics



Fig. 5 - Normalized On-Resistance vs. Drain Current

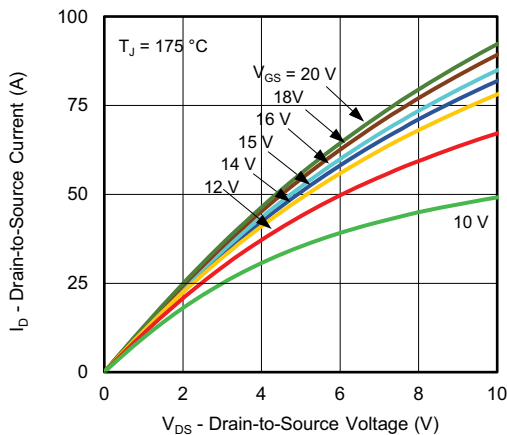


Fig. 3 - Typical Output Characteristics

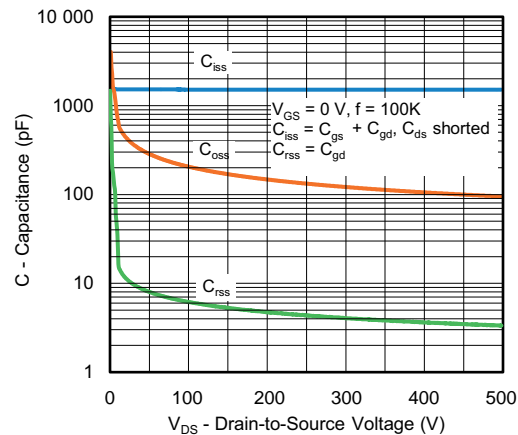


Fig. 6 - Typical Capacitance vs. Drain-to-Source Voltage

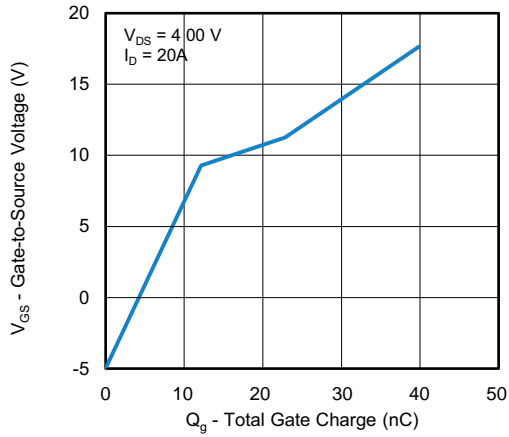


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

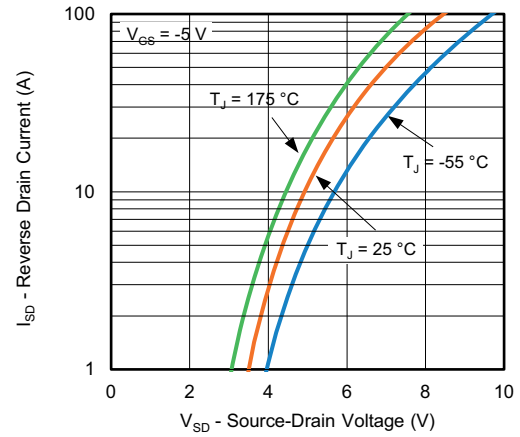


Fig. 10 - Typical Source-Drain Diode Forward Voltage

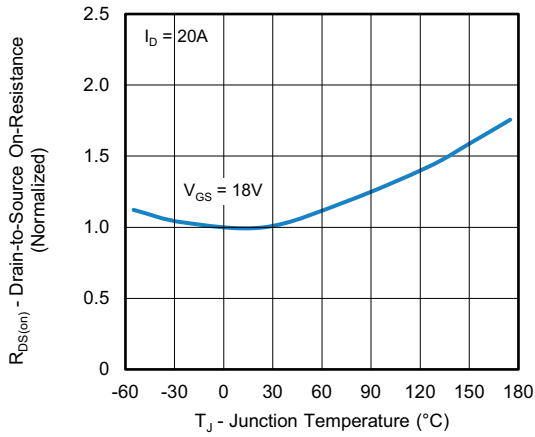


Fig. 8 - Normalized On-Resistance vs. Temperature

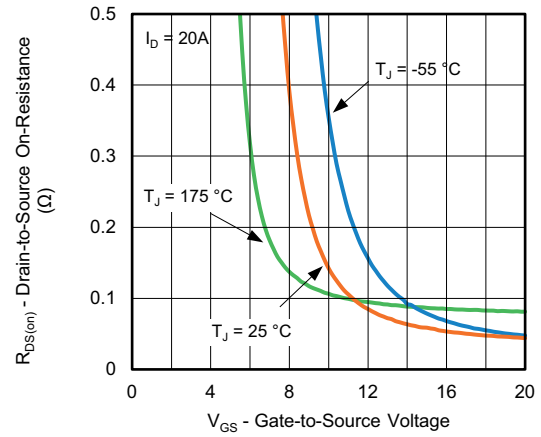


Fig. 11 - On-Resistance vs. Gate-to-Source Voltage

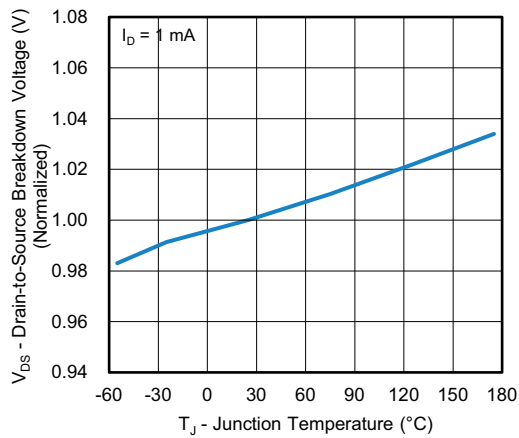


Fig. 9 - Drain-to-Source Voltage vs. Temperature

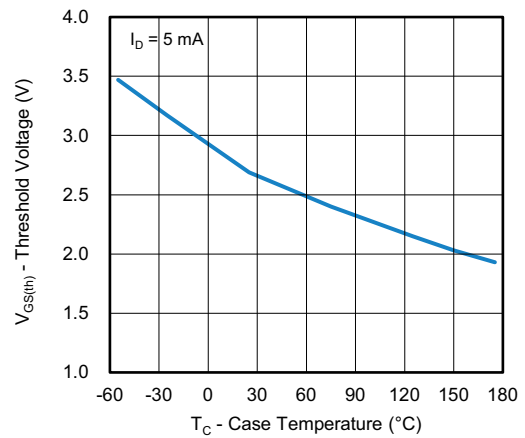


Fig. 12 - Threshold Voltage vs. Case Temperature

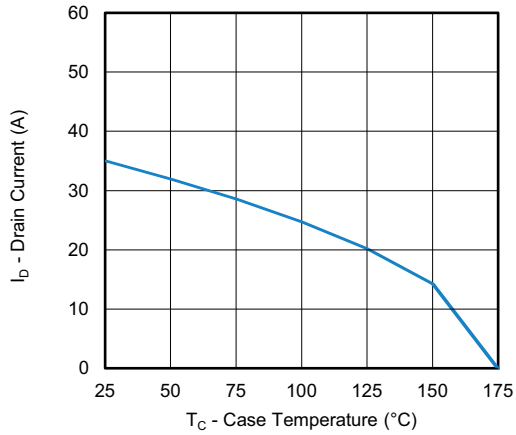


Fig. 13 - Drain Current vs. Case Temperature

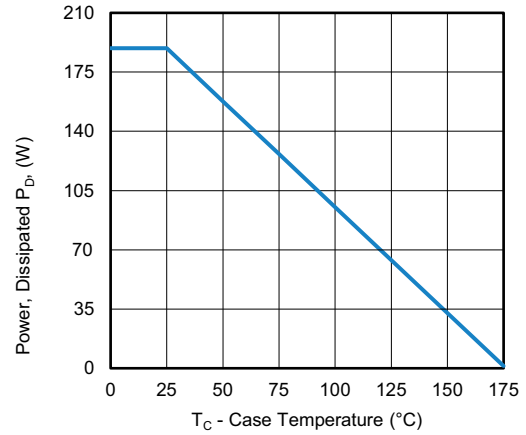


Fig. 15 - Power, Dissipated P_D vs. Case Temperature

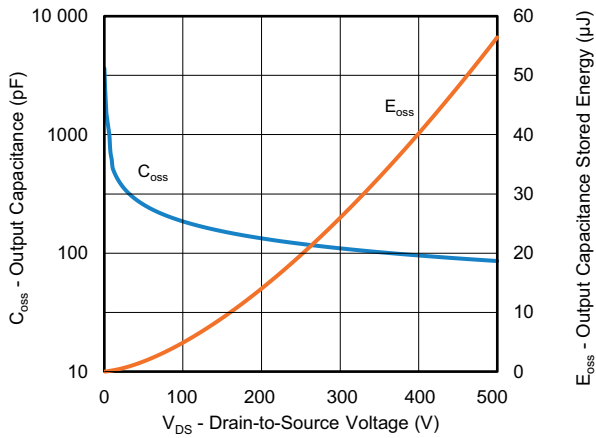


Fig. 14 - Output Capacitance and its Stored Energy vs. Drain-to-Source Voltage

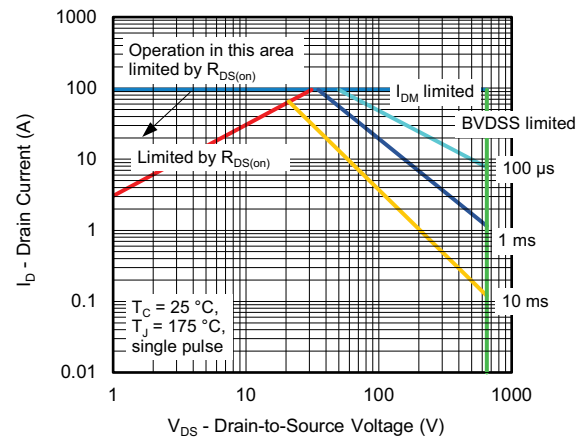


Fig. 16 - Safe Operating Area

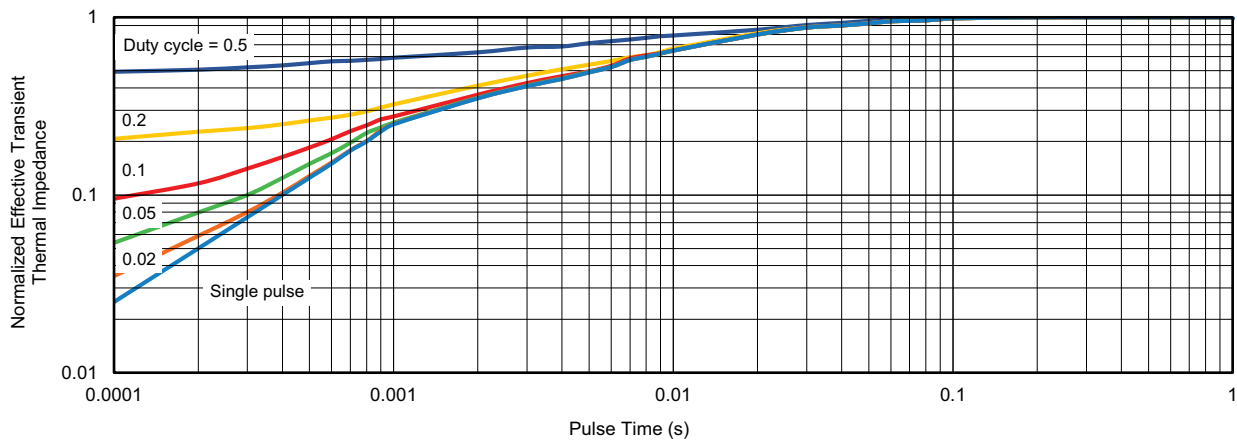


Fig. 17 - Transient Thermal Impedance

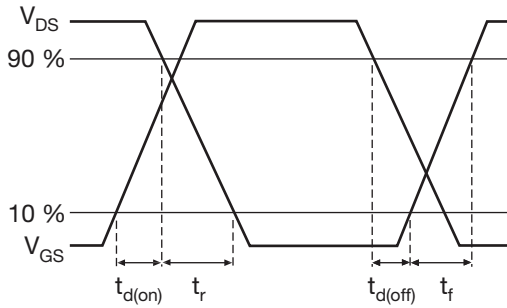


Fig. 18 - Waveforms of Switching Time

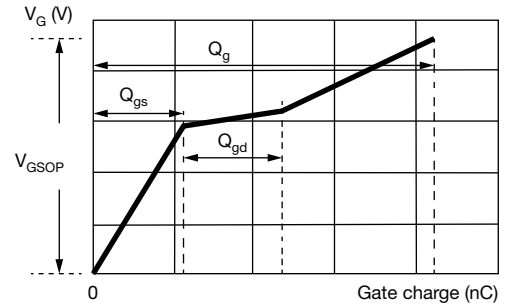


Fig. 21 - Waveforms for Gate Charge

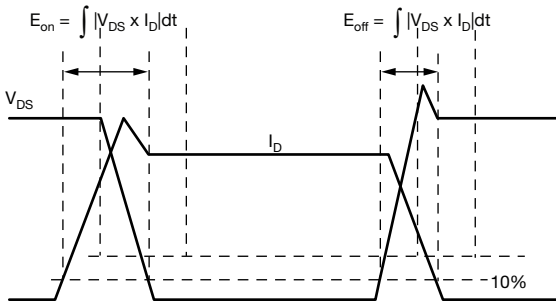


Fig. 19 - Waveforms for Switching Energy

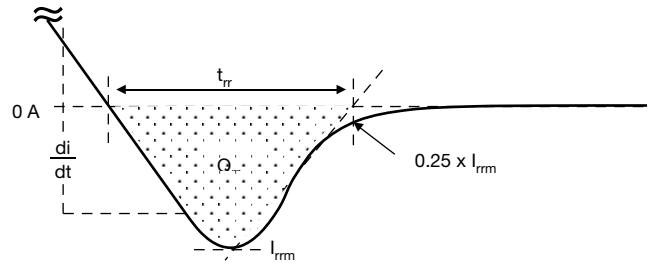


Fig. 22 - Waveforms for Reverse Recovery

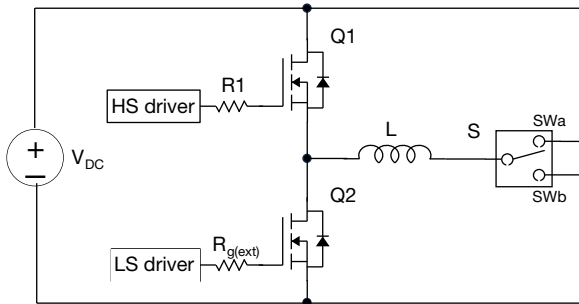


Fig. 20 - Switching and Reverse Diode Characteristics Measurement Circuit

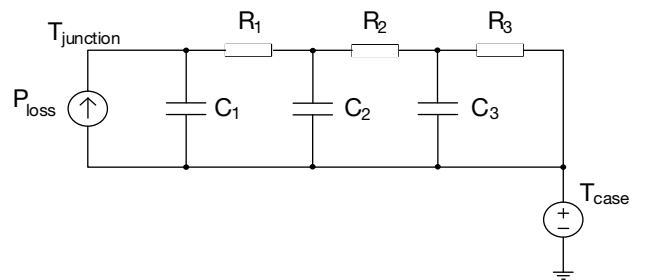
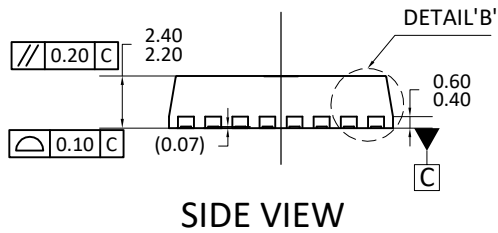
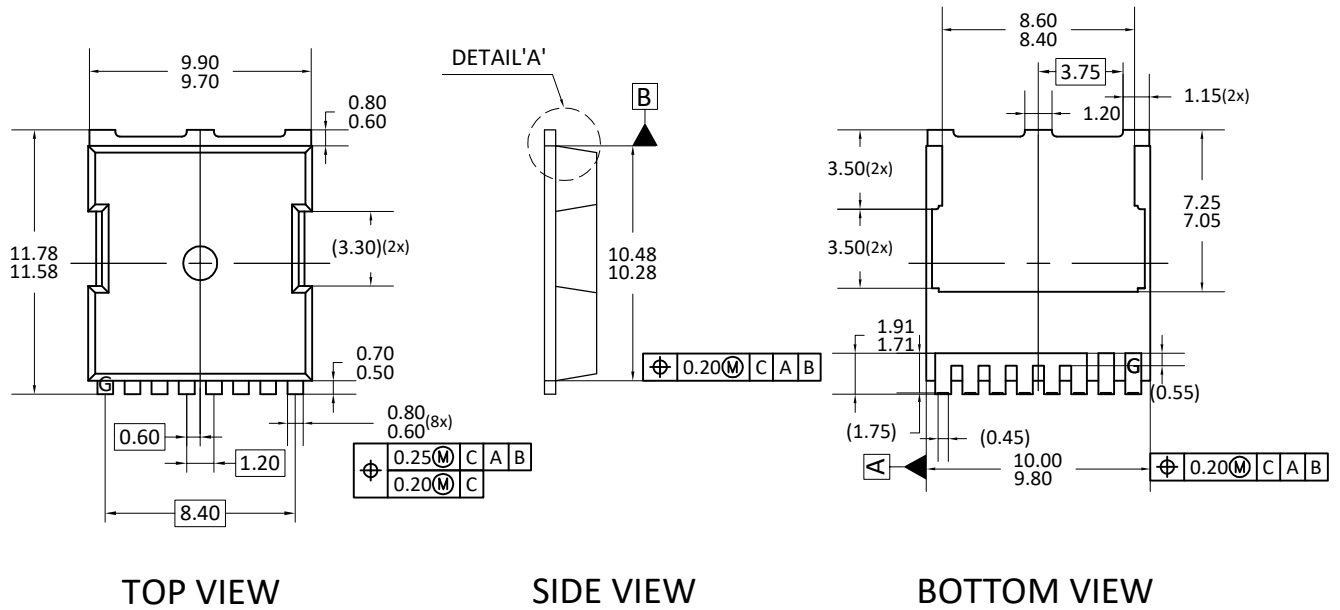


Fig. 23 - Thermal Equivalent Circuit

TOLL PACKAGE OUTLINE



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